

101341C

RD500-100-10W-500 MHz Dispersive Delay Line 100 MHz Bandwidth

Specifications

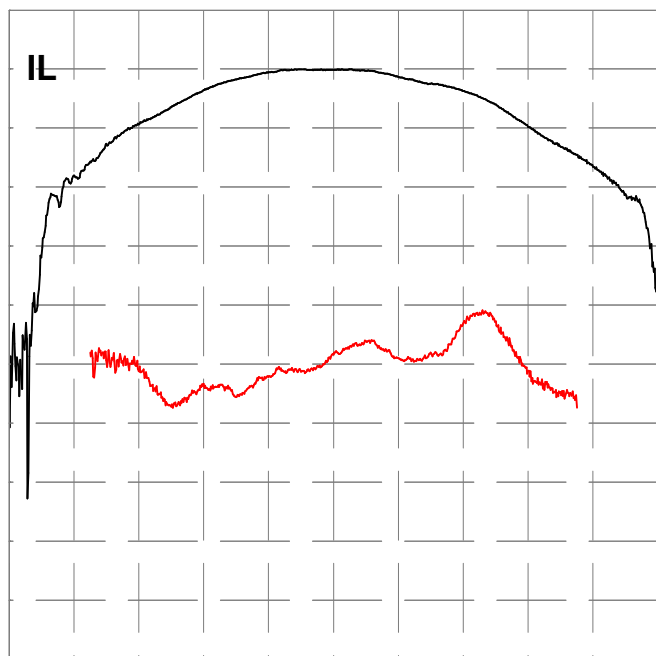
Parameter	Symbol	Min	Typical	Max	Unit
Center Frequency	F_0		500		MHz
Bandwidth	B		100		MHz
Dispersion	T		10		μsec
Delay	T_0	7.4	7.444	7.48	μsec
Insertion Loss	IL		35.2	39	dB
Slope	S_0	-0.0982	-0.098	-0.0977	$\mu\text{s}/\text{MHz}$
Pulse Width at -3dB			0.0118	0.0124	μsec
Sidelobes for $ t - T_0 < T$			-28.7	-24	dB
Time Spurious for $ t - T_0 > T$			-66	-60	dB
Substrate Material		YZ-LN			

Notes

- Center Frequency (F_0) and Bandwidth (B) are defined, not measured. Dispersion (T) is defined as $|B * S_0|$.
- Insertion Loss is the minimum loss for $|f - F_0| < .5B$
- Delay and Slope determined by best fit quadratic pulse in $|f - F_0| < .5B$.
- Specifications are at 22 °C only. Unit will operate undamaged from -54 °C to 125 °C with shifts $dF_0 = -x * F_0$, $dT_0 = x * (T_0 + S_0 * F_0)$, $dS_0 = x * 2 * S_0$, where $x = 94E-6 * (\text{temperature} - 22 \text{ °C})$

Typical Performance

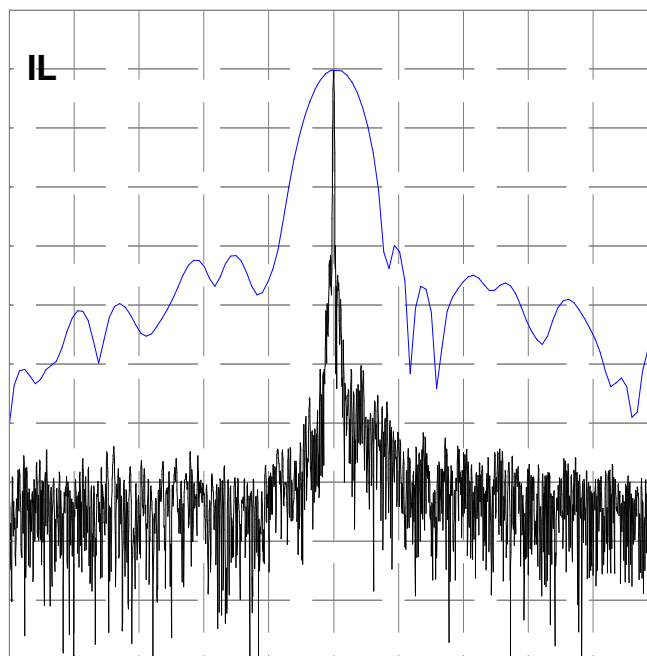
Frequency Response
(Best Fit Quadratic Phase Removed)



10 dB/div, 10 deg/div, 12.000 MHz/div

Compressed Pulse Response

FFT(Frequency Response * Cos(0.5 * PI * MIN(1, MAX(0, |f - F0| * 10.0 / B - 5.0)))^2)

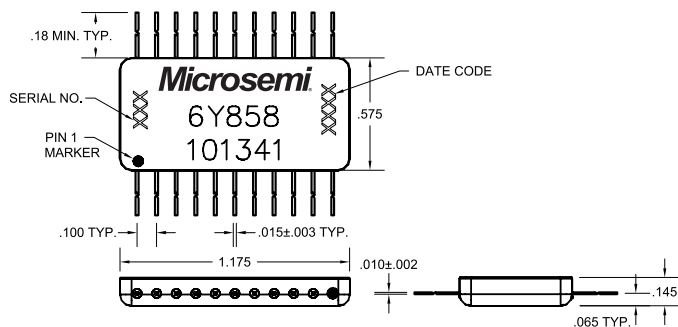


10 dB/div, 0.667 us/div, 0.020 us/div

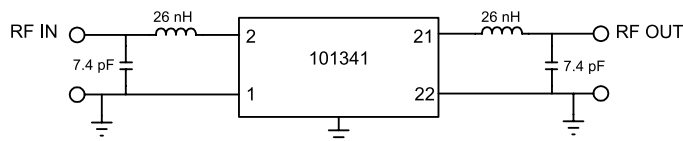
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Package Outline



Matching



Microsemi Corporate Headquarters

One Enterprise, Aliso Viejo, CA 92656 USA

Within the USA: +1 (800) 713-4113

Outside the USA: +1 (949) 380-6100

Fax: +1 (949) 215-4996

Email: sales.support@microsemi.com

www.microsemi.com

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